

TPCA8A09-H

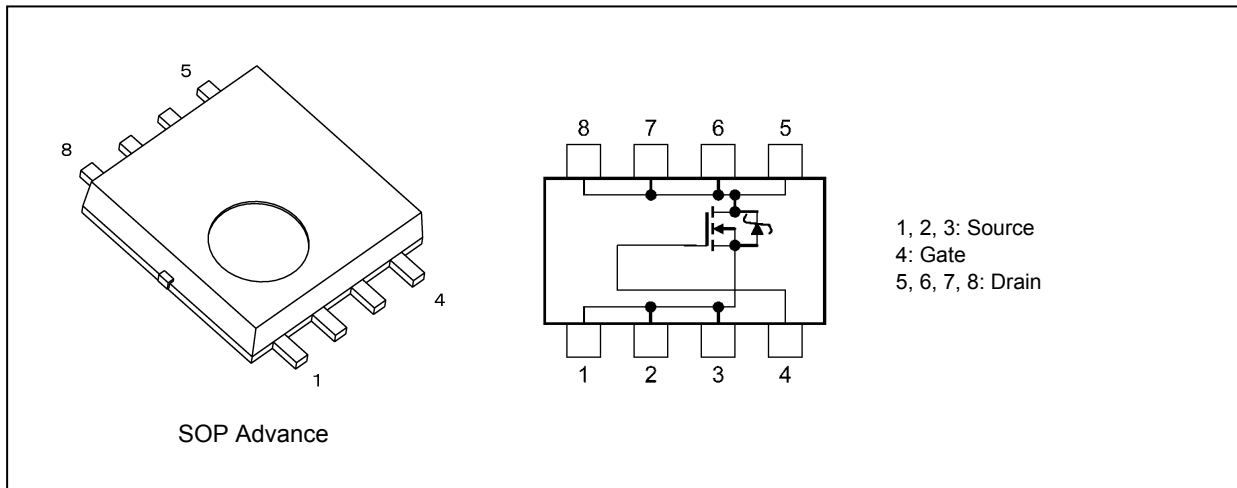
1. Applications

- High-Efficiency DC-DC Converters
- Notebook PCs
- Mobile Handsets

2. Features

- (1) Built-in a schottky barrier diode
Low forward voltage: $V_{DSF} = -0.6\text{ V (max)}$
- (2) High-speed switching
- (3) Small gate charge: $Q_{SW} = 17\text{ nC (typ.)}$
- (4) Low drain-source on-resistance: $R_{DS(ON)} = 2.2\text{ m}\Omega\text{ (typ.) (}V_{GS} = 4.5\text{ V)}$
- (5) Low leakage current: $I_{DSS} = 100\text{ }\mu\text{A (max) (}V_{DS} = 30\text{ V)}$
- (6) Enhancement mode: $V_{th} = 1.3\text{ to }2.3\text{ V (}V_{DS} = 10\text{ V, }I_D = 1\text{ mA)}$

3. Packaging and Internal Circuit



4. Absolute Maximum Ratings (Note) ($T_a = 25^\circ\text{C}$ unless otherwise specified)

Characteristics	Symbol	Rating	Unit
Drain-source voltage	V_{DSS}	30	V
Gate-source voltage	V_{GSS}	± 20	
Drain current (DC) (Note 1)	I_D	51	A
Drain current (pulsed) (Note 1)	I_{DP}	153	
Power dissipation ($T_C = 25^\circ\text{C}$)	P_D	70	W
Power dissipation ($t = 10\text{ s}$) (Note 2)	P_D	2.8	W
Power dissipation ($t = 10\text{ s}$) (Note 3)	P_D	1.6	W
Single-pulse avalanche energy (Note 4)	E_{AS}	338	mJ
Avalanche current	I_{AR}	51	A
Channel temperature	T_{ch}	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to 150	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

5. Thermal Characteristics

Characteristics	Symbol	Max	Unit
Channel-to-case thermal resistance ($T_C = 25^\circ\text{C}$)	$R_{th(ch-c)}$	1.78	$^\circ\text{C/W}$
Channel-to-ambient thermal resistance ($t = 10\text{ s}$) (Note 2)	$R_{th(ch-a)}$	44.6	$^\circ\text{C/W}$
Channel-to-ambient thermal resistance ($t = 10\text{ s}$) (Note 3)	$R_{th(ch-a)}$	78.1	$^\circ\text{C/W}$

Note 1: Ensure that the channel temperature does not exceed 150°C .

Note 2: Device mounted on a glass-epoxy board (a), Figure 5.1

Note 3: Device mounted on a glass-epoxy board (b), Figure 5.2

Note 4: $V_{DD} = 24\text{ V}$, $T_{ch} = 25^\circ\text{C}$ (initial), $L = 0.1\text{ mH}$, $R_G = 1\ \Omega$, $I_{AR} = 51\text{ A}$

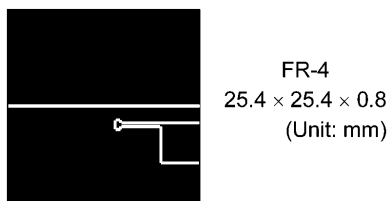


Fig. 5.1 Device Mounted on a Glass-Epoxy Board (a)

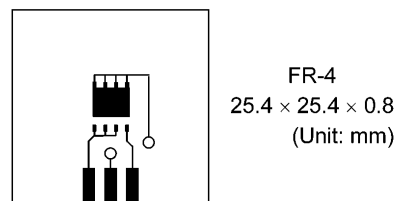


Fig. 5.2 Device Mounted on a Glass-Epoxy Board (b)

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

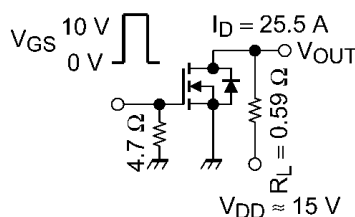
6. Electrical Characteristics

6.1. Static Characteristics ($T_a = 25^\circ\text{C}$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current	I_{GSS}	$V_{GS} = \pm 20\text{ V}, V_{DS} = 0\text{ V}$	—	—	± 0.1	μA
Drain cut-off current	I_{DSS}	$V_{DS} = 30\text{ V}, V_{GS} = 0\text{ V}$	—	—	100	
Drain-source breakdown voltage	$V_{(BR)DSS}$	$I_D = 10\text{ mA}, V_{GS} = 0\text{ V}$	30	—	—	V
	$V_{(BR)DSX}$	$I_D = 10\text{ mA}, V_{GS} = -20\text{ V}$	15	—	—	
Gate threshold voltage	V_{th}	$V_{DS} = 10\text{ V}, I_D = 1\text{ mA}$	1.3	—	2.3	
Drain-source on-resistance	$R_{DS(ON)}$	$V_{GS} = 4.5\text{ V}, I_D = 25.5\text{ A}$	—	2.2	2.8	$\text{m}\Omega$
		$V_{GS} = 10\text{ V}, I_D = 25.5\text{ A}$	—	1.7	2.3	

6.2. Dynamic Characteristics ($T_a = 25^\circ\text{C}$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Input capacitance	C_{iss}	$V_{DS} = 10\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	—	5900	7100	pF
Reverse transfer capacitance	C_{rss}		—	250	370	
Output capacitance	C_{oss}		—	1100	—	
Gate resistance	r_g	$V_{DS} = 10\text{ V}, V_{GS} = 0\text{ V}, f = 5\text{ MHz}$	—	1.4	2.1	Ω
Switching time (rise time)	t_r	See Figure 6.2.1.	—	5.3	—	ns
Switching time (turn-on time)	t_{on}		—	14	—	
Switching time (fall time)	t_f		—	10	—	
Switching time (turn-off time)	t_{off}		—	55	—	



Duty $\leq 1\%$, $t_w = 10\ \mu\text{s}$

Fig. 6.2.1 Switching Time Test Circuit

6.3. Gate Charge Characteristics ($T_a = 25^\circ\text{C}$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Q_g	$V_{DD} \approx 24\text{ V}, V_{GS} = 10\text{ V}, I_D = 51\text{ A}$	—	82	—	nC
		$V_{DD} \approx 24\text{ V}, V_{GS} = 5\text{ V}, I_D = 51\text{ A}$	—	41	—	
Gate-source charge 1	Q_{gs1}	$V_{DD} \approx 24\text{ V}, V_{GS} = 10\text{ V}, I_D = 51\text{ A}$	—	18	—	
Gate-drain charge	Q_{gd}		—	8.0	—	
Gate switch charge	Q_{sw}		—	17	—	

6.4. Source-Drain Characteristics ($T_a = 25^\circ\text{C}$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Reverse drain current (pulsed) (Note 5)	I_{DRP}	—	—	—	153	A
Diode forward voltage	V_{DSF}	$I_{DR} = 2\text{ A}, V_{GS} = 0\text{ V}$	—	-0.4	-0.6	V
		$I_{DR} = 51\text{ A}, V_{GS} = 0\text{ V}$	—	—	-1.2	

Note 5: Ensure that the channel temperature does not exceed 150°C .

7. Marking

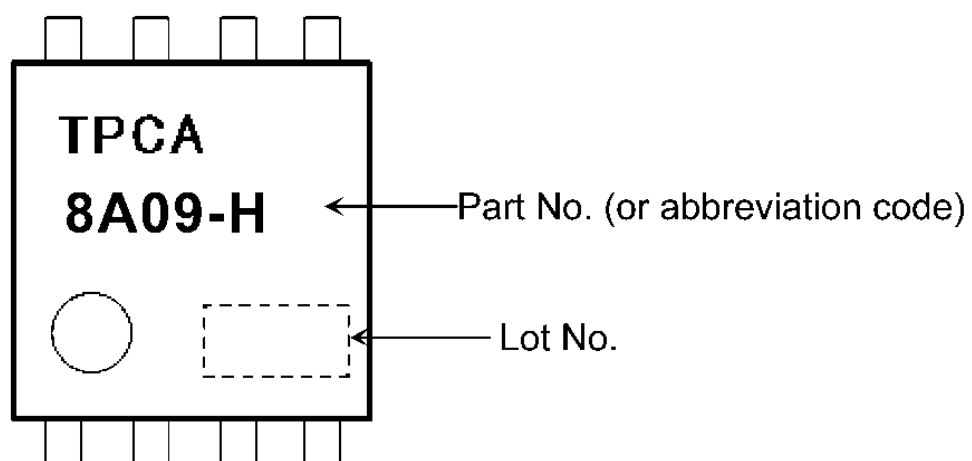


Fig. 7.1 Marking

8. Characteristics Curves (Note)

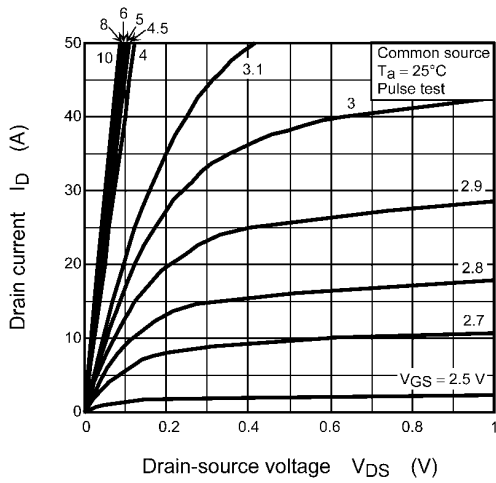


Fig. 8.1 ID - VDS

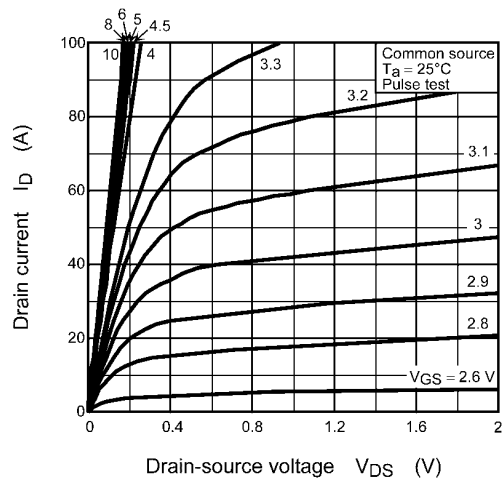


Fig. 8.2 ID - VDS

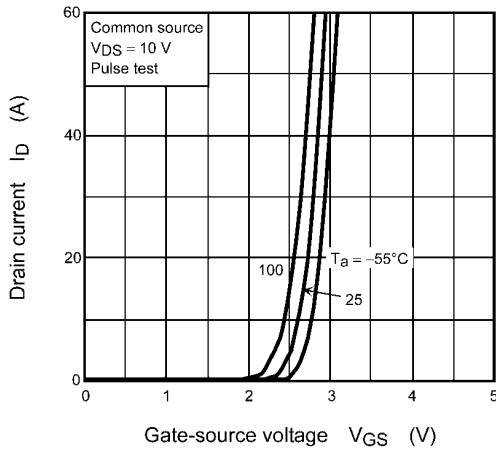


Fig. 8.3 ID - VGS

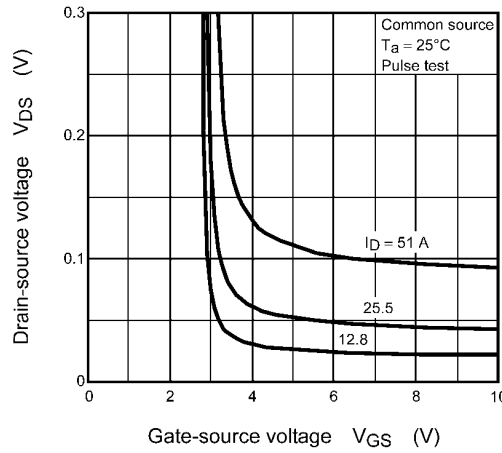


Fig. 8.4 VDS - VGS

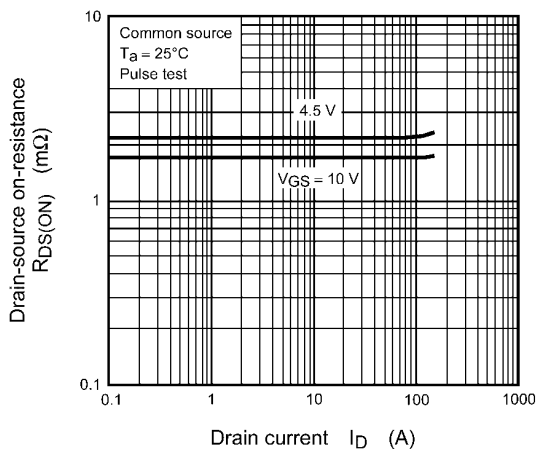


Fig. 8.5 RDS(ON) - ID

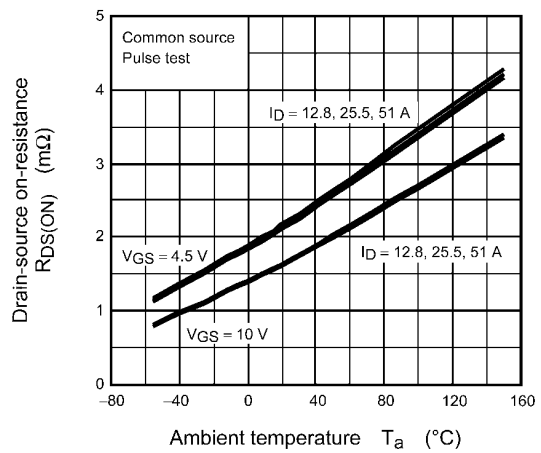


Fig. 8.6 RDS(ON) - Ta

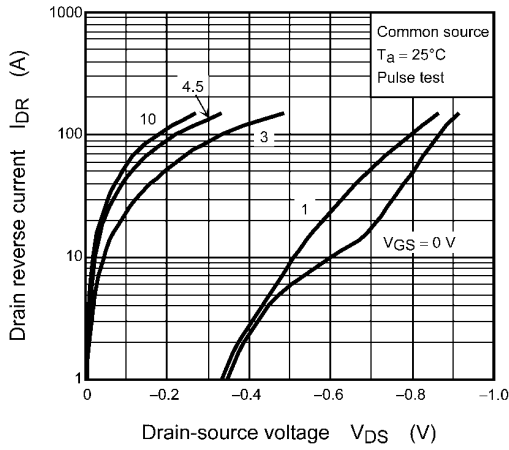


Fig. 8.7 $I_{DR} - V_{DS}$

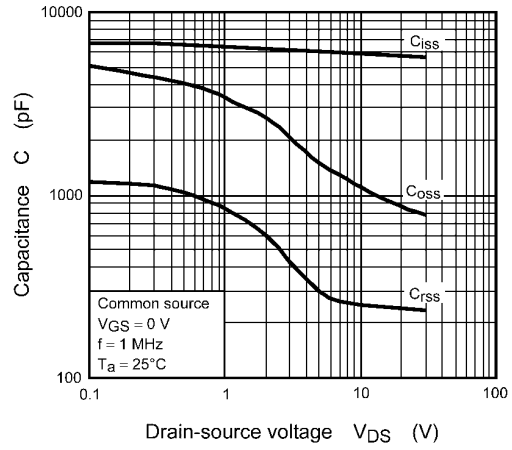


Fig. 8.8 Capacitance - V_{DS}

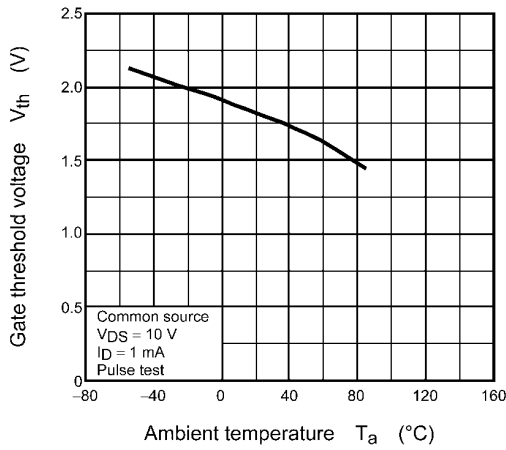


Fig. 8.9 $V_{th} - T_a$

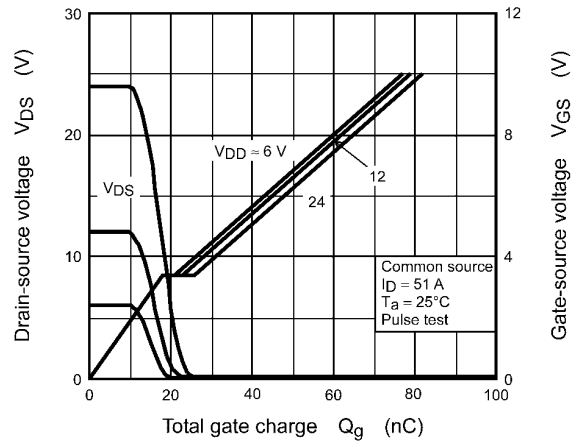


Fig. 8.10 Dynamic Input/Output Characteristics

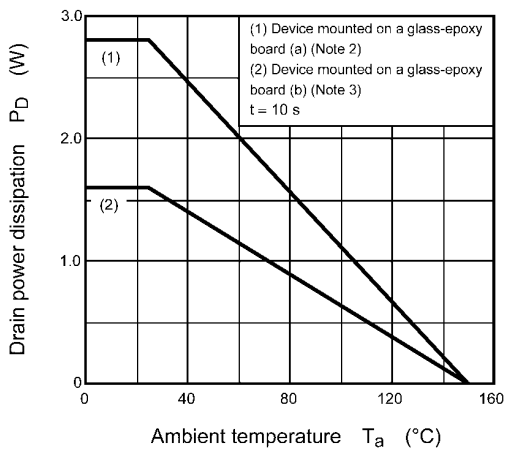


Fig. 8.11 $P_D - T_a$
 (Guaranteed Maximum)

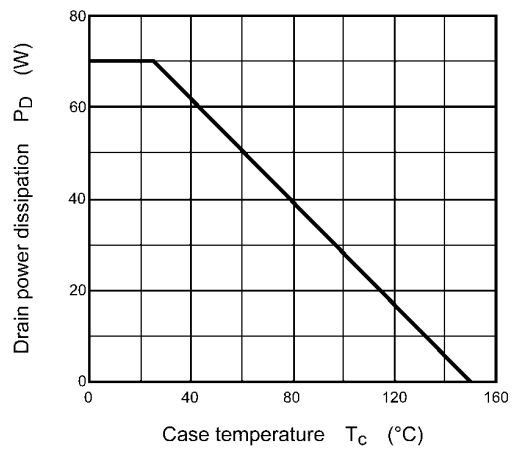


Fig. 8.12 $P_D - T_c$
 (Guaranteed Maximum)

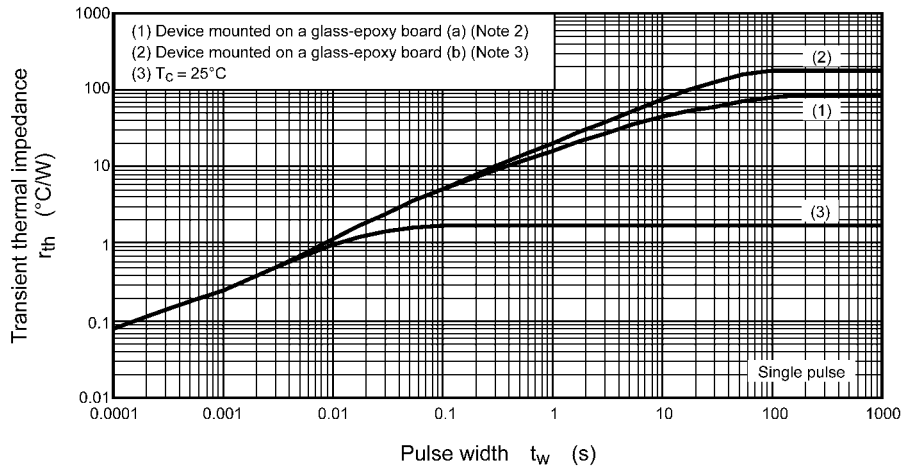


Fig. 8.13 $r_{th} - t_w$
(Guaranteed Maximum)

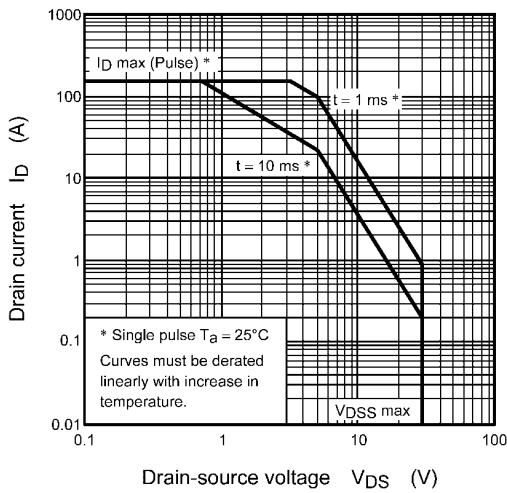


Fig. 8.14 Safe Operating Area
(Guaranteed Maximum)

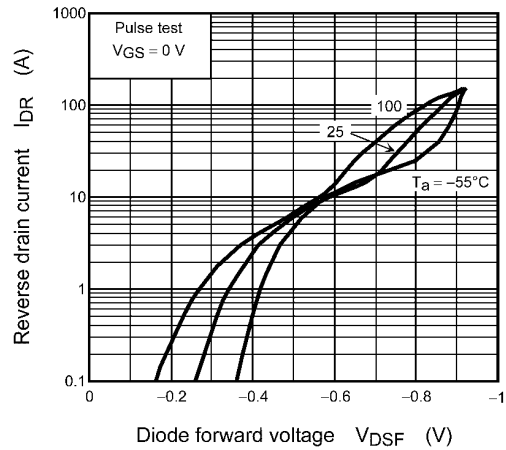


Fig. 8.15 $I_{DR} - V_{DSF}$

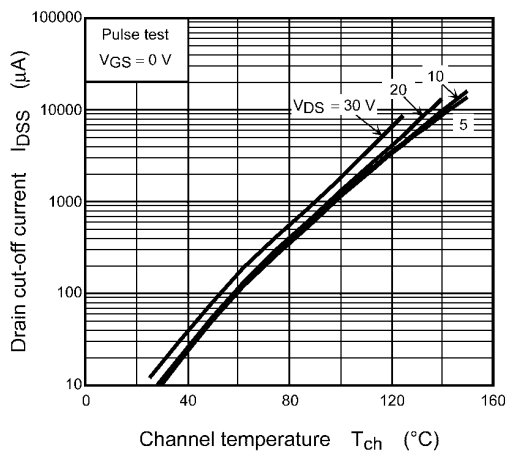


Fig. 8.16 $I_{DSS} - T_{ch}$

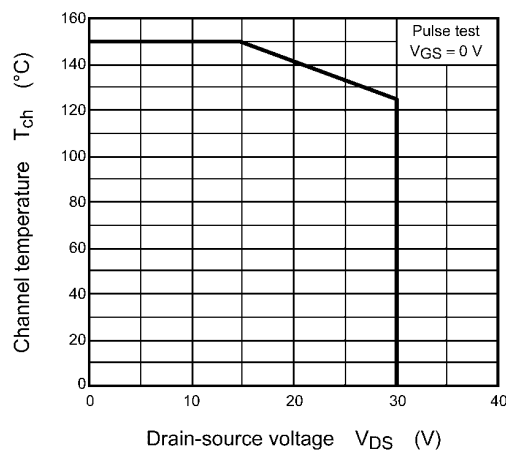
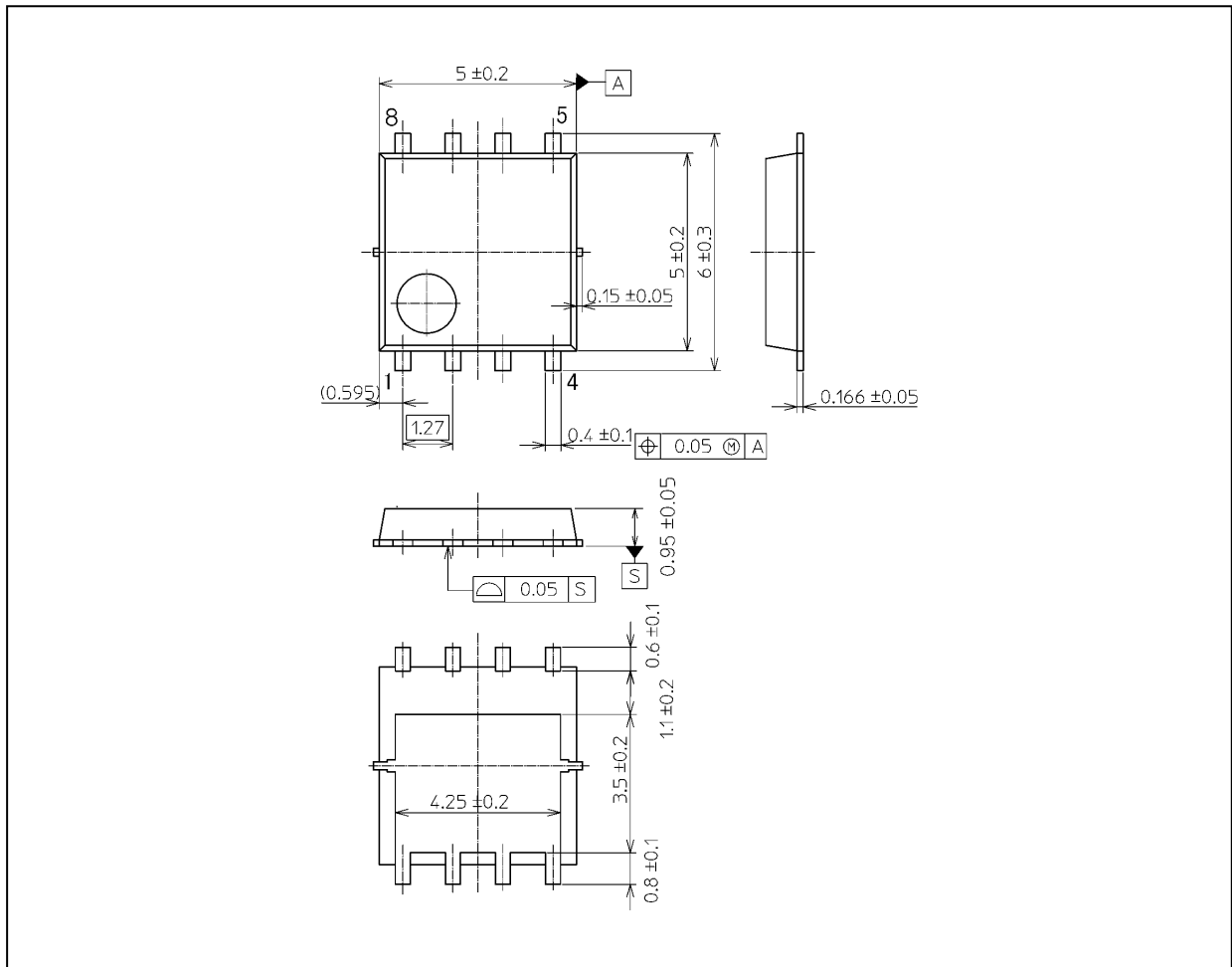


Fig. 8.17 $T_{ch} - V_{DS}$
(Guaranteed Maximum)

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

Package Dimensions

Unit: mm



Weight: 0.069 g (typ.)

Package Name(s)
TOSHIBA: 2-5Q1S
Nickname: SOP Advance

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